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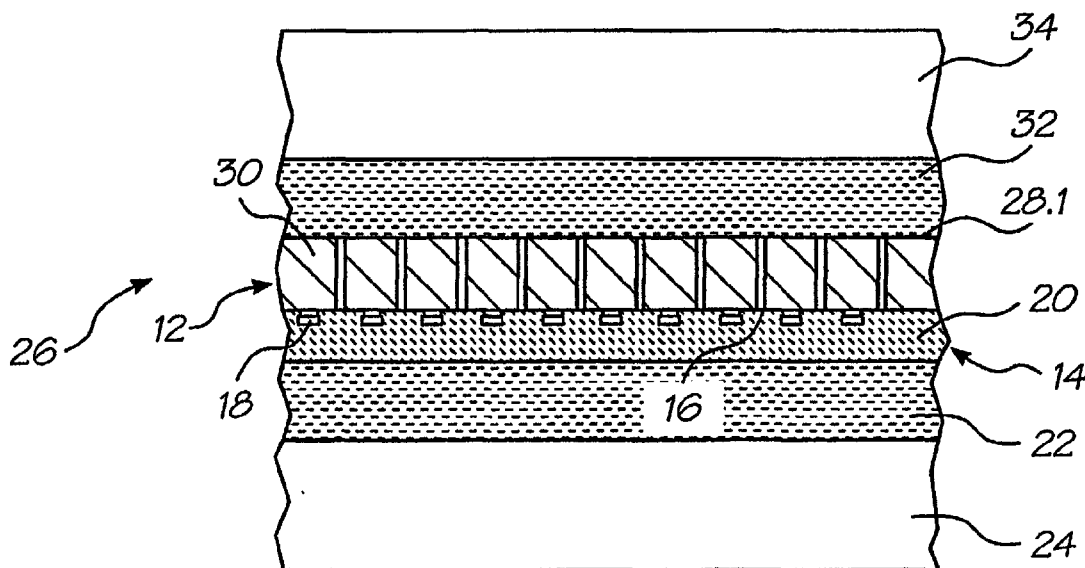
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4) Title: METHOD OF FABRICATING DEVICES INCORPORATING MICROELECTROMECHANICAL SYSTEMS USING
/ CURABLE TAPES



(57) Abstract: A method of fabricating devices incorporating microelectromechanical systems (MEMS) using UV curable tapes includes providing a silicon substrate (12) with a MEMS layer (14) arranged on one side of the substrate (12). A first UV curable tape (22) is applied to the MEMS layer (14). At least one operation is performed on the substrate (14) via an opposed side of the substrate (14). A second UV curable tape (32) is applied to the opposed side of the substrate (14) and the first tape (22) is removed by exposing it to UV light. At least one operation is performed on the MEMS layer to form individual MEMS chips which are able to be removed individually from the second UV tape (32) by localised exposure of the tape (32) to UV light.

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